

BGA Heat Sink - High Performance maxiFLOW w/Thermal Tape



ATS Part#:	ATS-52270P-C1-R0
Description:	27.00 x 27.00 x 17.50 mm BGA Heat Sink - High Performance maxiFLOW w/Thermal Tape
Heat Sink Type:	maxiFLOW
Heat Sink Attachment:	Thermal Tape
Equivalent Part Number:	ATS-52270P-C2-R0

*Image above is for illustration purpose only.

Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- Fabricated from extruded aluminum, which minimizes thermal resistance from the base to the fins, reduces weight and keeps costs low
- Higher performance helps ensure reliable product life at a lower cost than other extruded heat sinks

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	3.7 °C/W	3 °C/W	2.6 °C/W	2.3 °C/W	2.1 °C/W	2 °C/W	1.9 °C/W
	Ducted Flow	2.9	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish
	27.00 mm	27.00 mm	17.50 mm	48.36 mm	T412	BLUE-ANODIZED
Notes: • Dimension A and B refer to component size. • Dimension C is the heat sink height from the bottom of the base to the top of the fin field. • ATS-52270P-C2-R0 is the exact heat sink assembly with an equivalent thermal interface material (Saint-Gobain C675). • Thermal performance data are provided for reference only. Actual performance may vary by application. • ATS reserves the right to update or change its products without notice to improve the design or performance. • ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant. • Contact ATS to learn about custom options available.						

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